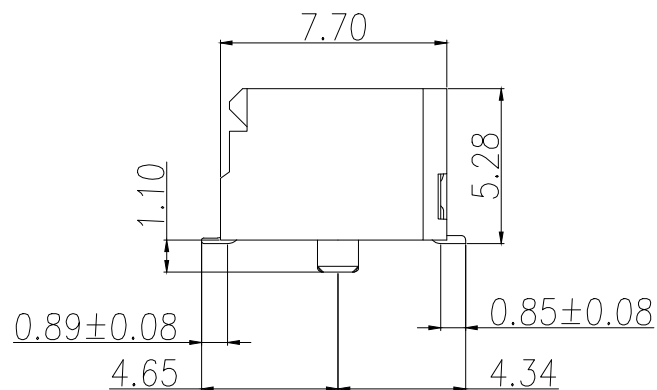
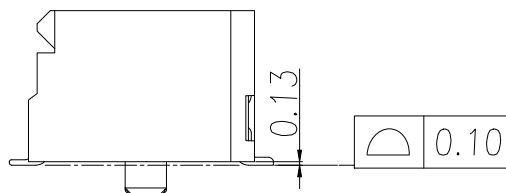
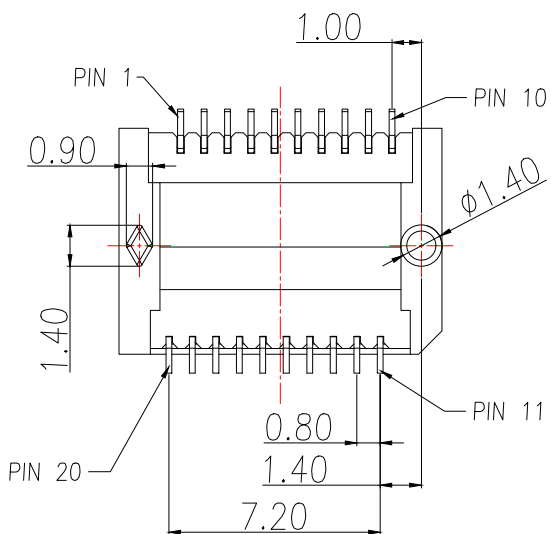
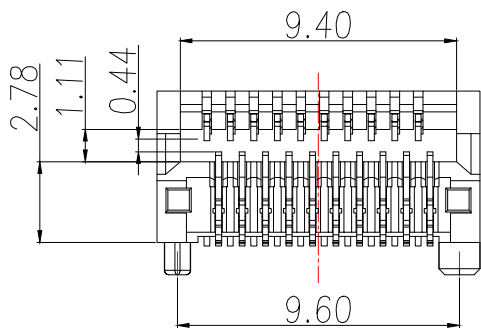
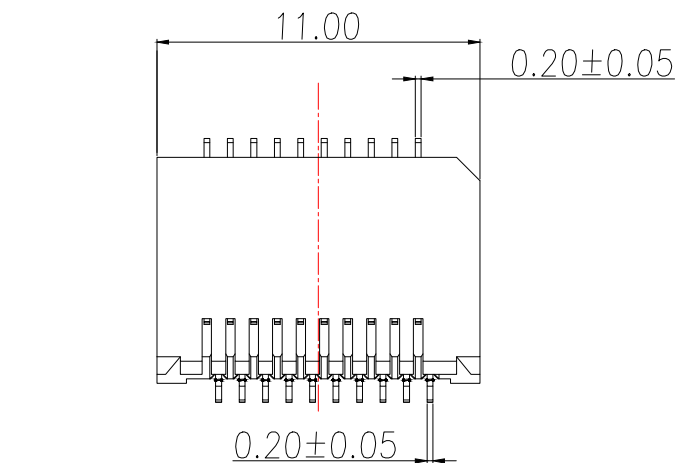




NOTES:

1.MATERIAL

HOUSING:HIGH TEMPERATURE LCP, Black,UL94 V-0

2.CONTACTS:PHOSPHOR BRONZE

PLATING :15μ"GOLD ON MATING AREA,
GOLD FLASH PLATING ON
SOLDER TAILS,50μ"NICKEL
UNDERPLATING OVERALL.

3.MECHANICAL REQUIREMENT:

3.1 DURABILITY:100 CYCLES MIN.

3.2 INSERTION AND EXTRACTION FORCE:40N MAX.& 11.5N MAX

4.ENVIRONMENTAL:

4.1 CONTACT RESISTANCE:20 MILLIOHMS MAXINITIAL.

4.2 DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN

4.3 CURRENT RATING:0.5 Amps Max.

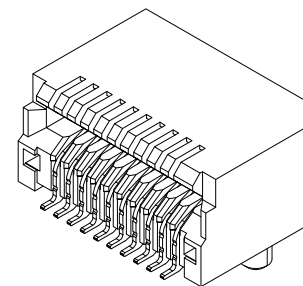
4.4 OPERATION:-40°C TO +95°C

4.5 STORAGE:-55°C TO +105°C

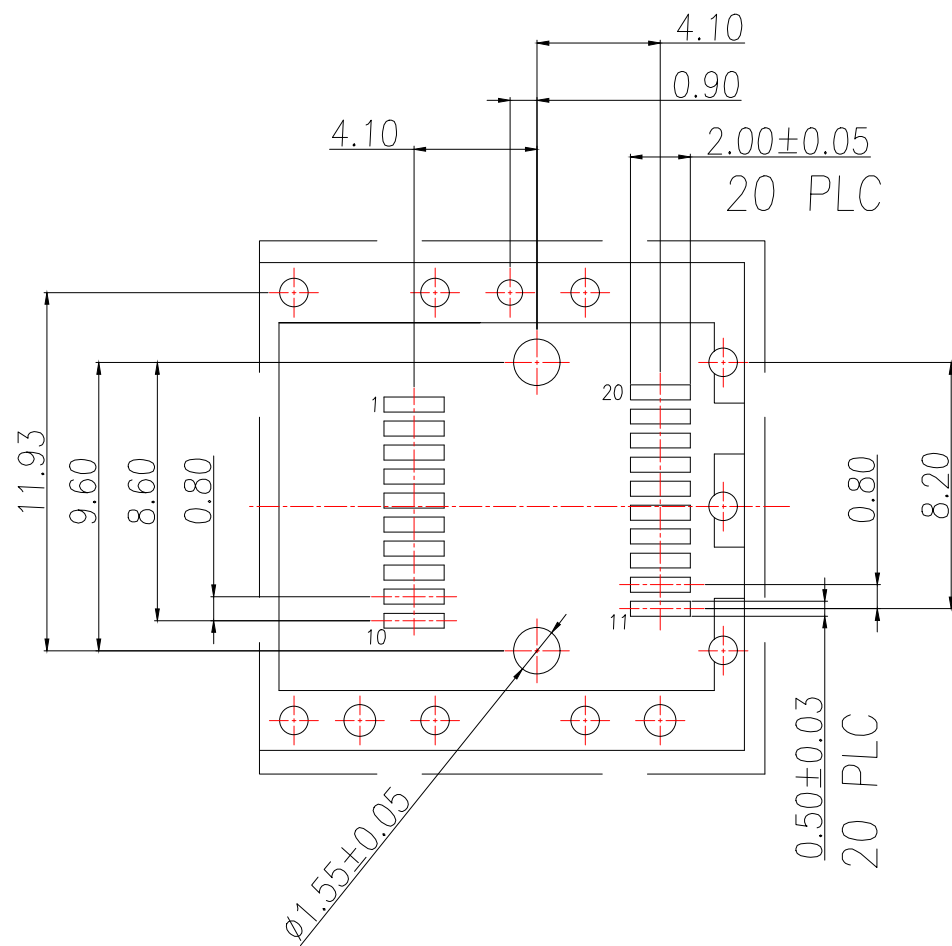
4.6 REFLOW SOLDERING TEMPERATURE:255~265°MAXIMUMFOR 5~10 SECONDS

4.9 ROHS COMPLIANT

5.PACKAGING:TAPE AND REEL

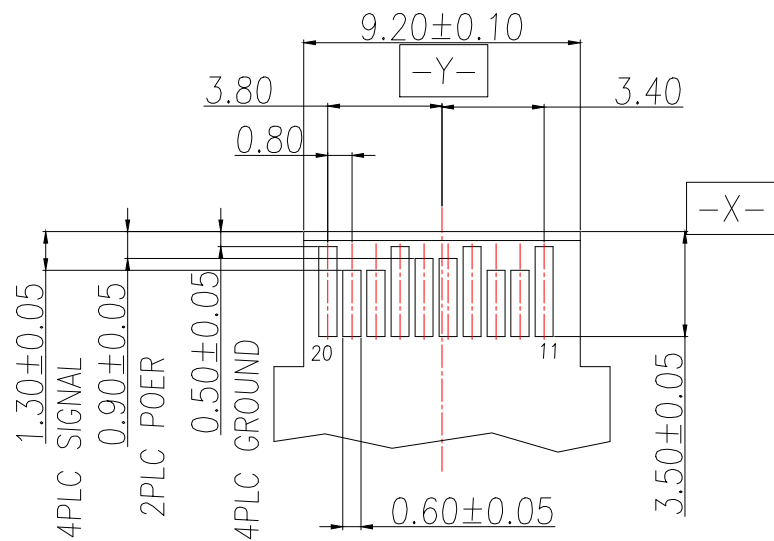


制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA	料号 PART NO.	BX-SFP-20P	版本 REV.	A
			.X±0.30	X.:±5°						
			.XX±0.25	X.X':±1°	审核 CHECK	EVA	品名 TITLE	SFP+ 1X1CONNECTOR	页次 SHEET	1/1
			.XXX±0.15		核准 APPROVAL	JADE	客户料号 CUTM.NO.			
			单位 UNITS		MM	比例 SCALE	1:1	Bossie (博锡)		

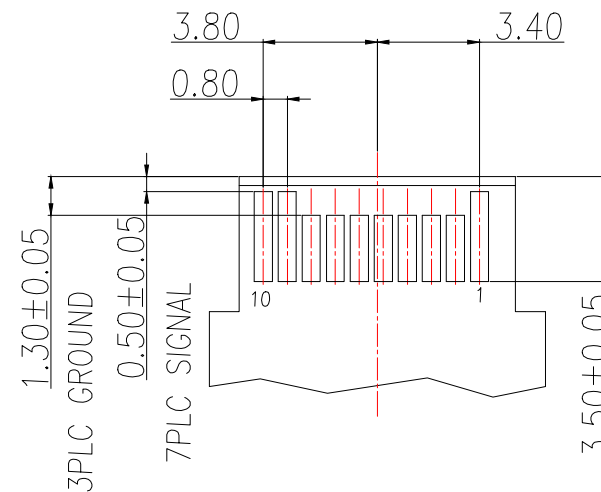
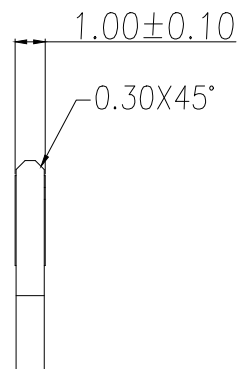


PCB.WELDING DRAWING (TOLERANCE:±0.05)

制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA			料号 PART NO.	BX-SFP-20P	版本 REV.	A
			.X±0.30	X.*:±5°					品名 TITLE	SFP+ 1X1CONNECTOR	页次 SHEET	1/1
			.XX±0.25	X.X*:±1°					客户料号 CUTM.NO.			
			.XXX±0.15						核准 APPROVAL	JADE		
					单位 UNITS	MM	比例 SCALE	1:1	 Bossie (博锡)			

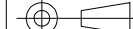


TOP VIEW OF BOARD



BOTTOM VIEW OF BOARD

RECOMMENDED LAYOUT DETAIL MATING TRANSCEIVER PCB

制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA			料号 PART NO.	BX-SFP-20P		版本 REV.	A
			.X±0.30	X.°:±5°	审核 CHECK	EVA			品名 TITLE	SFP+ 1X1CONNECTOR	页次 SHEET	1/1	
					核准 APPROVAL	JADE			客户料号 CUTM.NO.				
						单位 UNITS	MM	比例 SCALE	1:1				
			.XX±0.25	X.X°:±1°									
			.XXX±0.15										